

Product data sheet

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FEATURES

IEC61000-4-2 (ESD) ±30kV (Contact)

±30kV (Air)

- ♦ IEC61000-4-4 (EFT) 40A (5/50ηs)
- ♦ Protects one I/O line (bidirectional)
- ♦ Low clamping voltage
- ♦ Working voltages:
 - 3.3V,5V,8V,12V,15V,18V,20V,24V,36V
- ♦ Low leakage current

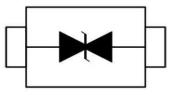
MACHANICAL DATA

- ♦ SOD-323 package
- ♦ Flammability Rating: UL 94V-0
- ♦ Packaging: Tape and Reel
- ♦ High temperature soldering guaranteed: 260°C/10s
- ♦ Reel size: 7 inch
- \diamond MSL 1

APPLICATIONS

- ♦ Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Networking and Telecom
- ♦ Serial and Parallel Ports.
- ♦ Peripherals

PIN CONFIGURATION





SOD-323

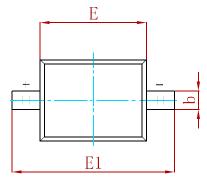


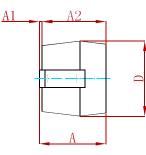
| ABSOLUTE MAXIMUM RATING | | | | | | |
|-------------------------|---------------------------------|---------------|-------|--|--|--|
| Symbol | Parameter | Value | Units | | | |
| V | ESD per IEC 61000-4-2 (Contact) | ±30 | | | | |
| VESD | ESD per IEC 61000-4-2 (Air) | ±30 | kV | | | |
| P _{PP} | Peak Pulse Power (8/20µs) | 350 | W | | | |
| T _{OPT} | Operating Temperature | -55/+150 | °C | | | |
| T _{STG} | Storage Temperature | -55/+150 | °C | | | |
| TL | Lead Soldering Temperature | 260 (10 sec.) | °C | | | |

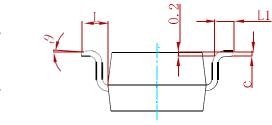
| ELECTRICAL CHARACTERISTICS (Tamb=25°C) | | | | | | | | | |
|--|------|-----------|--------|----------------|--------------------|--------|------|----------------|--------|
| | | V_{RWM} | Vв | Ι _Τ | V _c @1A | V | ′c | I _R | Ст |
| P/N | MARK | (V) | (V) | (mA) | (V) | (V) | | (µA) | (pF) |
| | | (max.) | (min.) | | (max.) | (max.) | (@A) | (max.) | (max.) |
| SD03C-MS | 2A | 3.3 | 4.0 | 1 | 7.5 | 16.0 | 20 | 40 | 450 |
| SD05C-MS | 2B | 5.0 | 6.0 | 1 | 9.8 | 18.0 | 17 | 10 | 200 |
| SD08C-MS | 2C | 8.0 | 8.5 | 1 | 13.4 | 24.0 | 15 | 2 | 120 |
| SD12C-MS | 2D | 12.0 | 13.3 | 1 | 19.0 | 32.0 | 11 | 1 | 75 |
| SD15C-MS | 2J | 15.0 | 16.7 | 1 | 24.0 | 38.0 | 10 | 1 | 68 |
| SD18C-MS | 2K | 18.0 | 20.0 | 1 | 29.0 | 45.0 | 9 | 1 | 57 |
| SD20C-MS | 2L | 20.0 | 22.3 | 1 | 35.0 | 50.0 | 8 | 1 | 52 |
| SD24C-MS | 2H | 24.0 | 26.7 | 1 | 43.0 | 52.0 | 7 | 1 | 50 |
| SD36C-MS | 2N | 36.0 | 40.0 | 1 | 60.0 | 75.0 | 4.5 | 1 | 35 |



PACKAGE MECHANICAL DATA

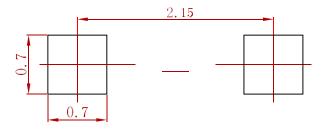






| Symbol | Dimensions | In Millimeters | Dimensions In Inches | | |
|--------|------------|----------------|----------------------|-------|--|
| Symbol | Min. | Max. | Min. | Max. | |
| A | | 1.000 | | 0.039 | |
| A 1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 0.800 | 0.900 | 0.031 | 0.035 | |
| b | 0.250 | 0.350 | 0.010 | 0.014 | |
| с | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 1.200 | 1.400 | 0.047 | 0.055 | |
| E | 1.600 | 1.800 | 0.063 | 0.071 | |
| E1 | 2.550 | 2.750 | 0.100 | 0.108 | |
| L | 0.475 REF. | | 0.019 REF. | | |
| L1 | 0.250 | 0.400 | 0.010 | 0.016 | |
| θ | 0° | 8° | 0° | 8° | |

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| | P/N | PKG | QTY | | |
|----------|-----|---------|------|--|--|
| SDXXC-MS | | SOD-323 | 3000 | | |
| | | | | | |





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